

## SPECIFICATION AMENDMENTS

Replace the paragraph at page 10, lines 7-14 with the following paragraph:

**FIGS. 2C and 2F** are enlarged cross-sectional views of photoresist layers 142 and 143144 formed on surfaces 122 and 124, respectively. Photoresist layers 142 and 143144 are simultaneously deposited as continuous dry films and then patterned by selectively applying light through respective reticles (not shown), applying a developer solution to remove the photoresist portions rendered soluble by the light, and then hard baking, as is conventional. As a result, photoresist layer 142 contains openings that selectively expose portions of surface 122, and photoresist layer 143144 contains openings that selectively expose portions of surface 124. Photoresist layers 142 and 143144 have a thickness of 15 microns.

Replace the paragraph at page 10, lines 15-28 with the following paragraph:

**FIGS. 2D and 2G** are enlarged cross-sectional views of various features formed in metal base 120 by wet chemical etching using photoresist layers 142 and 143144 as etch masks. In particular, the structure is dipped in a wet chemical etch that provides a front-side etch through the openings in photoresist layer 142 to the exposed portions of surface 122 and a back-side etch through the openings in photoresist layer 143144 to the exposed portions of surface 124. The structure is submerged in the wet chemical etch long enough for the etchant to etch about 120 microns into metal base 120. That is, the wet chemical etch provides a “half-etch” that removes slightly over one-half (120/200) the thickness of metal base 120 at the exposed portions. Thus, the front-side etch partially forms slot 128, the back-side etch partially forms slot 128 and completely forms recessed portion 132, and the combination of the front-side and back-side etches completely forms slot 128. Likewise, the front-side and back-side etches are applied simultaneously, and slot 128 and recessed portion 132 are formed simultaneously. The wet chemical etch also forms the other slots 128 and recessed portions 132 as well as recessed portions 134 and the unlabeled openings and notches in a similar manner.

Replace the paragraph at page 11, lines 4-5 with the following paragraph:

**FIGS. 2E and 2H** are enlarged cross-sectional views of metal base 120 after photoresist layers 142 and ~~143~~144 are simultaneously stripped.